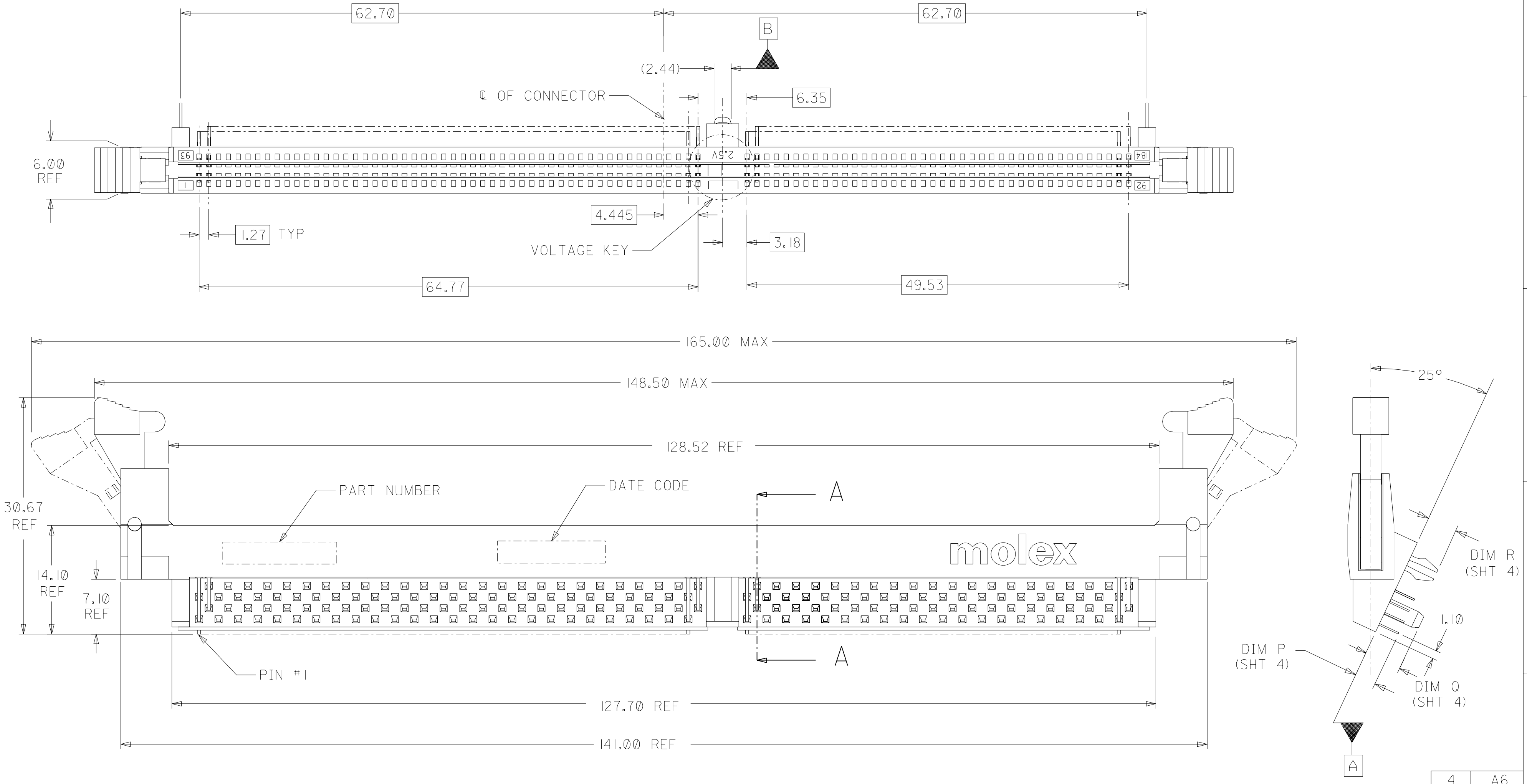


NOTES:

1. MATERIALS: HOUSING, BASEPLATE AND LATCH
   - HIGH TEMPERATURE THERMOPLASTIC, UL 94-V0
   TERMINAL AND FORKLOCK - COPPER ALLOY
2. FINISHES: CONTACT AREA: SEE TABLE ON SHEET 4
   SOLDER TAILS: 2.54uM/100u" MIN. TIN/LEAD
3. PRODUCT SPECIFICATIONS: PS-87623-002 FOR
   PERFORMANCE SPECIFICATIONS.
4. DATE CODE SHALL BE MARKED LEGIBLY AS SHOWN: XX XX
   YEAR — WEEK
5. PART NUMBER SHALL BE MARKED LEGIBLY AS SHOWN: 87623-0XXX
   REFER TO TABLE

SHT	REV
4	A6
3	A6
2	A6
1	A6

REVISE ON CAD ONLY

EC NO. S2003-0507
DRWN: VSKHOANG030415
CH'K: PT LIM 030513
APPR: SK TOH 030514

DESCRIPTION

A6

REV

QUALITY SYMBOLS
MAJOR ▼ = 0
CRITICAL ▽C = 0

GENERAL TOLERANCES:
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±0.---	±.
3 PLACES	±0.---	±.
2 PLACES	±0.25	±.
1 PLACE	±0.---	±.

ANGULAR: ± 5°

SCALE
NTS

DESIGN UNITS
☒mm ☐INCH

THIRD ANGLE PROJECTION

DIMENSIONS:
☐ mm/INCH ☐ INCH/mm ☒ mm ONLY

DRAWN BY & DATE
LPLIM 000110

CHECKED BY & DATE
DSOH 000202

APPROVED BY & DATE
TOH 000202

TITLE:
1.27 MM PITCH, 184 CKTS, 25 DEG DDR DIMM

MOLEX INCORPORATED

CAD FILENAME
SD-87623-001.S01

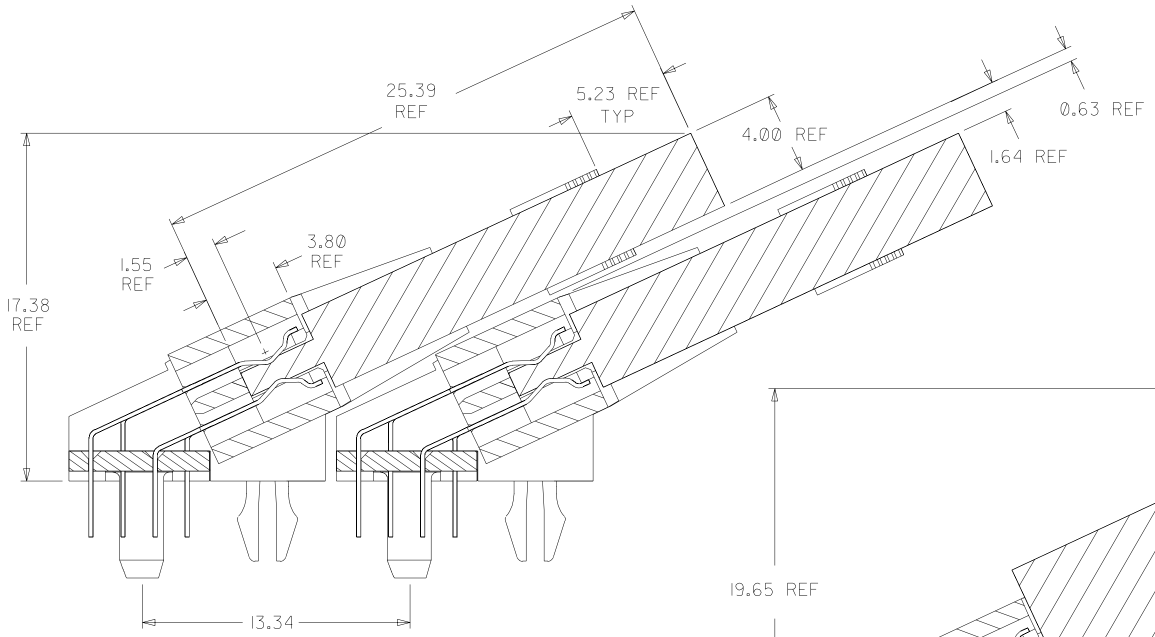
MATERIAL NO.
SEE TABLE

DRAWING NO.
SD-87623-001

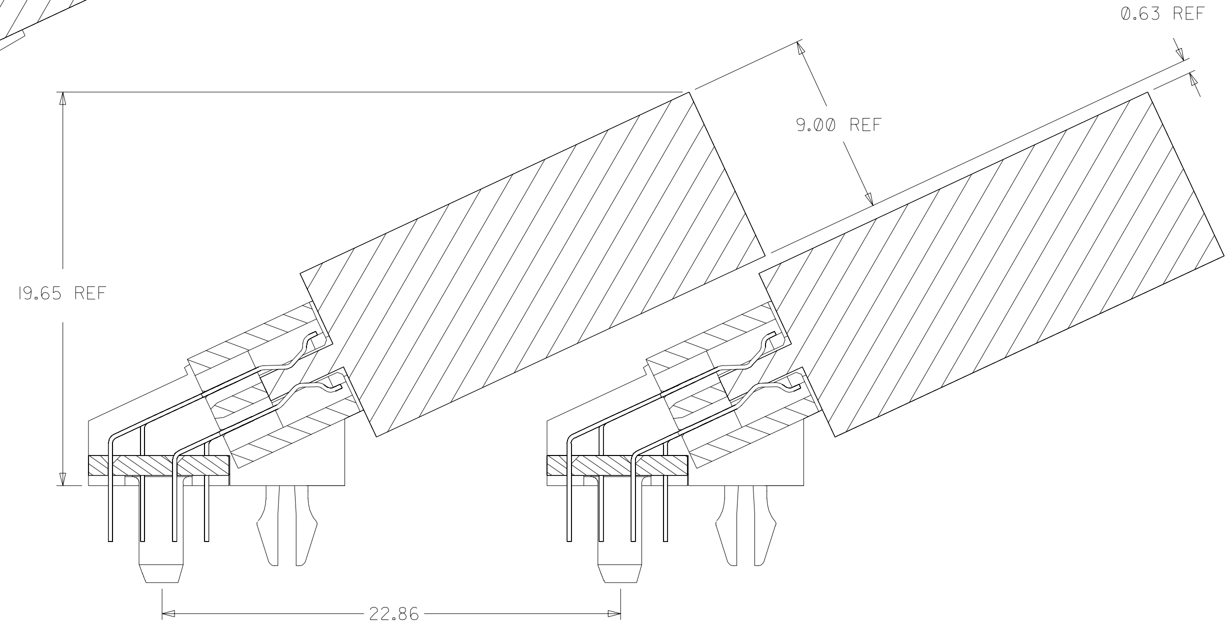
SHEET NO.
1 OF 4

SIZE
A3

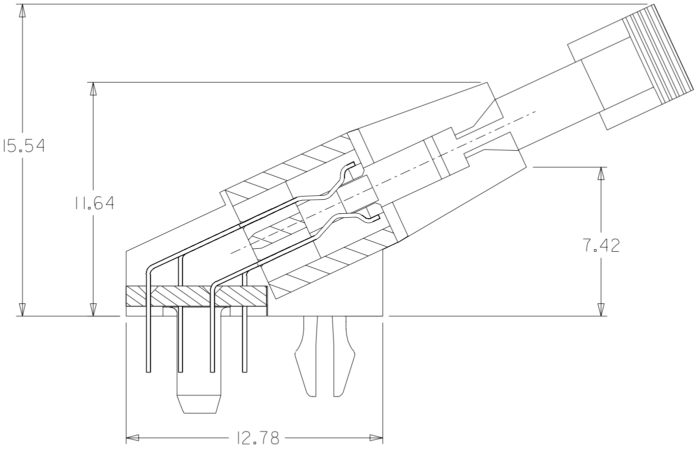
WBORD_A.BOR REV A
97/05/14 LEVEL 4



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 4.00 mm THICK
MODULE (TYPICAL TSOP PACKAGING)



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 9.00 mm THICK
MODULE (TYPICAL SOJ PACKAGING)



SECTION A-A

EC NO. S2003-0507
DRWN: VSKHOANG030415
CH'K: PT LIM 030513
APPR: SK TOH 030514
DESCRIPTION
A6
REV

QUALITY SYMBOLS
MAJOR ▼ = 0
CRITICAL ◇C = 0

GENERAL TOLERANCES:
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±0.---	±.
3 PLACES	±0.---	±.
2 PLACES	±0.25	±.
1 PLACE	±0.---	±.

ANGULAR: ± 5°

SCALE NTS
DESIGN UNITS ☒mm ☐INCH
THIRD ANGLE PROJECTION
DIMENSIONS: ☐ mm/INCH ☐ INCH/mm ☒ mm ONLY
SHT
REV
REVISE ON CAD ONLY
DRAWN BY & DATE LPLIM 000110
CHECKED BY & DATE DSOH 000202
APPROVED BY & DATE TOH 000202
TITLE:
1.27 MM PITCH, 184 CKTS, 25 DEG DDR DIMM
molex MOLEX INCORPORATED
CAD FILENAME SD-87623-001.S02
MATERIAL NO. SEE TABLE
DRAWING NO. SD-87623-001
SHEET NO. 2 OF 4
SIZE A3

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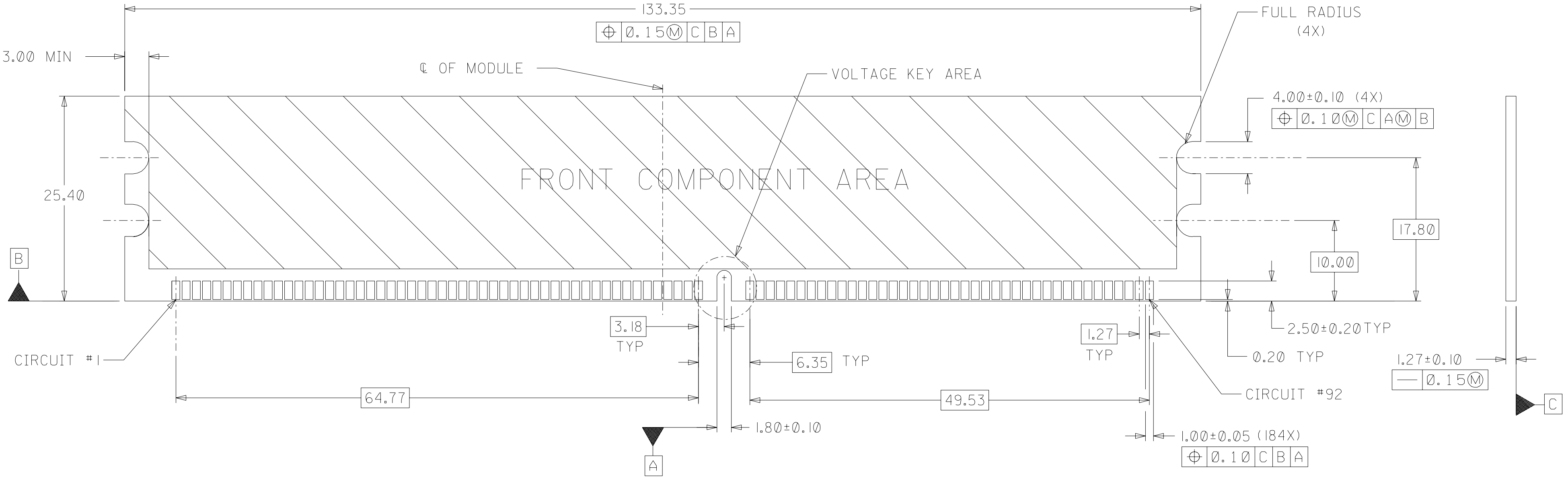
WBORD_A.BOR REV A
97/05/14 LEVEL 4

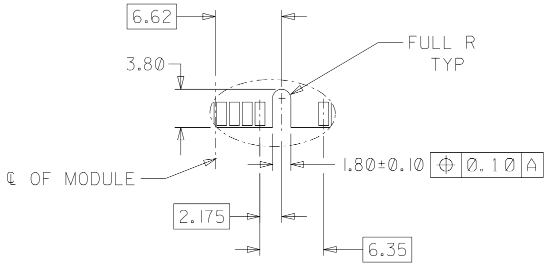


RECOMMENDED MODULE LAYOUT

(PER JEDEC STANDARD MO-206, 184 CKT.)

UNLESS OTHERWISE SPECIFIED, GENERAL TOLERANCE FOR MODULE = ±0.13

VOLTAGE KEY AREA



OFFSET LEFT KEY

(2.5 VOLTS)

EC NO. S2003-0507
DRWN: VSKHOANG030415
CH'K: PT LIM 030513
APPR: SK TOH 030514
DESCRIPTION
A6
REV

QUALITY SYMBOLS
MAJOR ▼ = 0
CRITICAL ▽C = 0

GENERAL TOLERANCES:
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±0.---	±.
3 PLACES	±0.---	±.
2 PLACES	±0.25	±.
1 PLACE	±0.---	±.

ANGULAR: ± 5 °

SCALE NTS
DESIGN UNITS ☒mm ☐INCH
THIRD ANGLE PROJECTION
DIMENSIONS: ☐ mm/INCH ☐ INCH/mm ☒ mm ONLY
SHT REV
REVISE ON CAD ONLY

DRAWN BY & DATE LPLIM 000110
CHECKED BY & DATE DSOH 000202
APPROVED BY & DATE TOH 000202

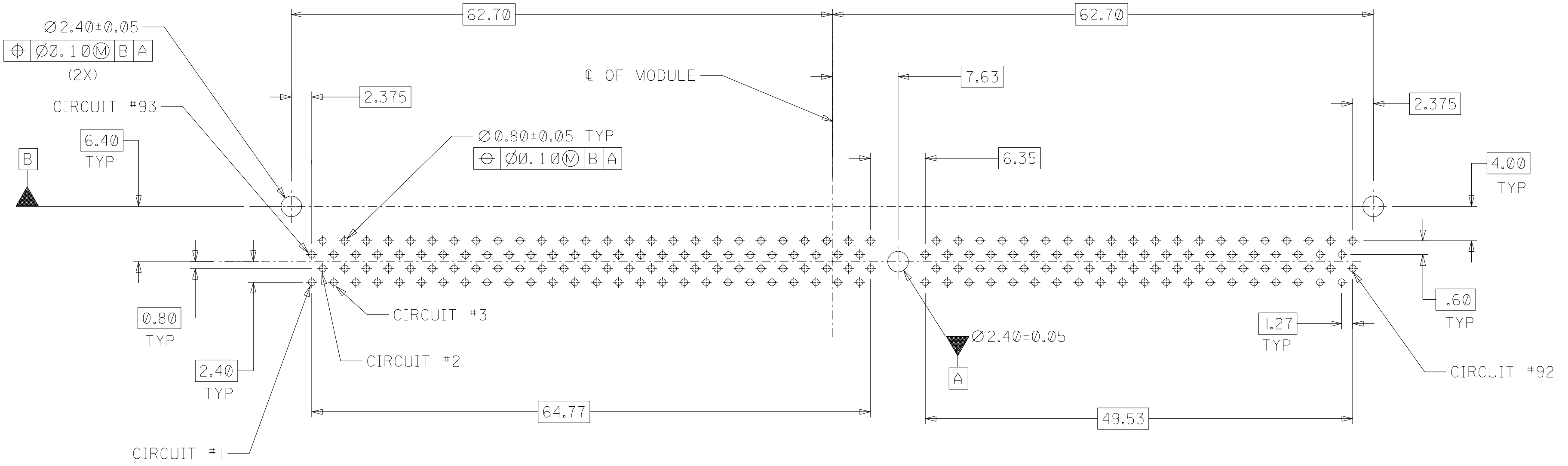
TITLE:
1.27 MM PITCH, 184 CKTS, 25 DEG DDR DIMM

MOLEX INCORPORATED

CAD FILENAME SD-87623-001.S03
MATERIAL NO. SEE TABLE
DRAWING NO. SD-87623-001
SHEET NO. 3 OF 4

SIZE A3

MATERIAL NO.	VOLTAGE KEY	CKT SIZE	TAIL LENGTH P±0.25	PEG LENGTH Q±0.25	FORK LENGTH R±0.25	RECOMMENDED PCB THICKNESS	FINISHES: CONTACT AREA
87623-0001	LEFT (2.5V)	184	2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.38uM/15u" MIN. GOLD OVER 1.27uM/50u" MIN. NICKEL
87623-0011			3.18	4.83	3.94		
87623-0012			3.18	3.18	3.18		
87623-0013			3.81	4.83	4.42	2.84	
87623-0101			2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.76uM/30u" MIN. GOLD OVER 1.27uM/50u" MIN. NICKEL
87623-0111			3.18	4.83	3.94		
87623-0113			3.81	4.83	4.42	2.84	



RECOMMENDED
P.C. BOARD HOLE PATTERN
(CONNECTOR SIDE)

EC NO. S2003-0507
DRWN:VSKHOANG030415
CH'K: PT LIM 030513
APPR:SK TOH 030514
DESCRIPTION
A6
REV

QUALITY SYMBOLS
MAJOR ▼ = 0
CRITICAL ▽ (C) = 0

GENERAL TOLERANCES:
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±0. ---	±.
3 PLACES	±0. ---	±.
2 PLACES	±0.25	±.
1 PLACE	±0. ---	±.

ANGULAR: ± 5 °

SCALE NTS
DESIGN UNITS ☒mm ☐INCH
THIRD ANGLE PROJECTION
DIMENSIONS: ☐ mm/INCH ☐ INCH/mm ☒ mm ONLY
SHT REV
REVISE ON CAD ONLY
DRAWN BY & DATE L.P.LIM 000110
CHECKED BY & DATE DSOH 000202
APPROVED BY & DATE TOH 000202
TITLE:
1.27 MM PITCH, 184 CKTS, 25 DEG DDR DIMM
MOLEX INCORPORATED
CAD FILENAME SD-87623-001.S04
MATERIAL NO. SEE TABLE
DRAWING NO. SD-87623-001
SHEET NO. 4 OF 4
SIZE A3

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